



EES-3000 series

Fanless Modular Box Computer



Features

- Scalable system with onboard CPU ranging from VIA Eden V4 1 GHz to AMD GX466
- Versatile LCD Display
- AC97 Audio
- Single or Dual LAN
- Rich I/O Interface
- 2.5" HDD, Type I/II CF
- Fanless with Special Thermal Design

Fanless

4 SBC Options

Multi-media

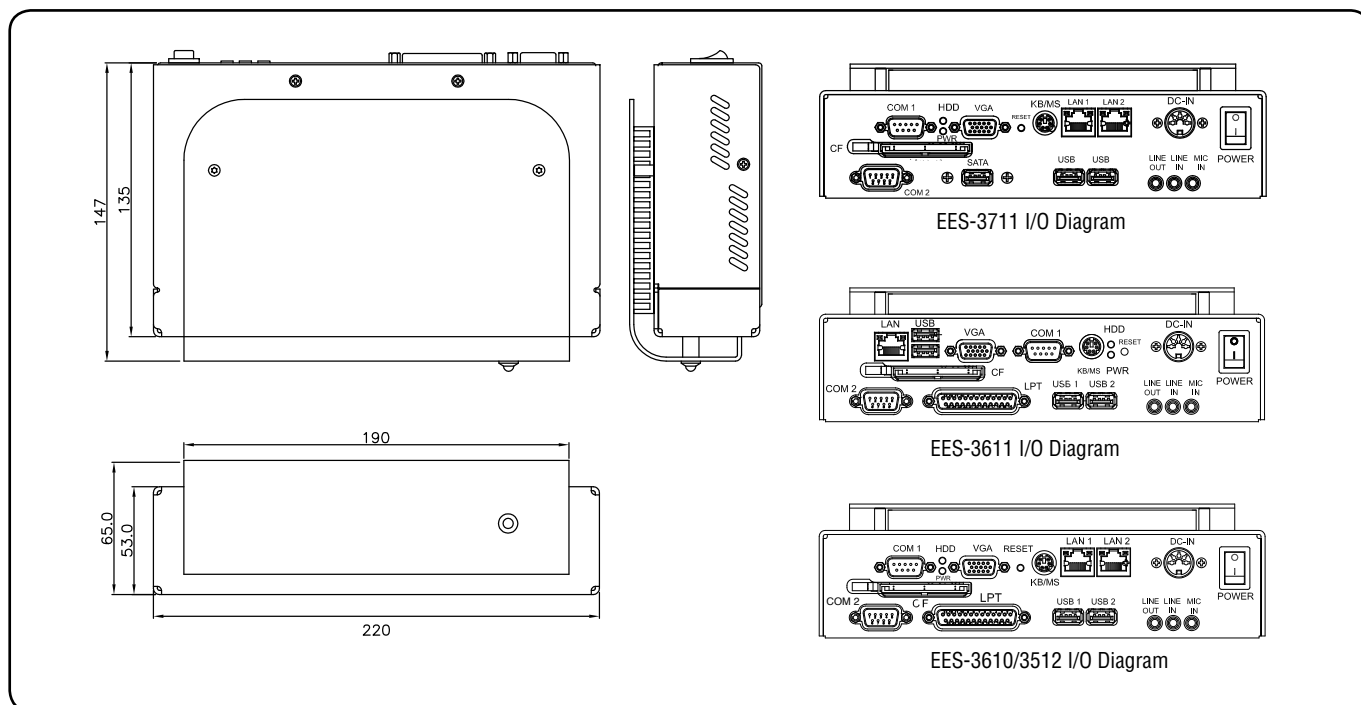
LAN/2 LAN

2 USB/4 USB

Specifications

Modular System	EES-3711	EES-3611	EES-3610	EES-3512
System Board Option	ECM-3711	ECM-3611	ECM-3610	ECM-3512
CPU	Onboard VIA Eden V4 1 GHz CPU	Onboard VIA Eden ESP10K 1 GHz	EES-3610B: Onboard VIA Eden ESP6000 667 MHz EES-3610B-E10: Onboard VIA Eden ESP10K 1 GHz	Onboard AMD Geode GX466 333 MHz
System Chipset	VIA CN700/VT8251	VIA CLE266 VT8623/VT8237R	VIA TwisterT VT8606/VT82C686B	AMD Geode GX466/CS5535
System Memory	One 200-pin SODIMM up to 1 GB DDR2 400/533 SDRAM	One 200-pin SODIMM up to 1 GB DDR200/266 SDRAM	One 144-pin SODIMM up to 512 MB SDRAM	One 200-pin SODIMM up to 512 MB DDR 200/266 SDRAM
SSD	Type I/II CF with ejector	Type I/II CF with ejector	Type I/II CF with ejector	Type I/II CF with ejector
Display	VIA ProSavage CN700 integrated 2D/3D gaphic engine	VIA CLE266 VT8623 with integrated UniChrome 2D/3D graphics with MPEG-2 decoder, and using system memory 64 MB	VIA VT8606 TwisterT integrated S3 Savage4 2D/3D graphics accelerator with 32 MB display memory	AMD Geode GX466 with integrated 2D graphics engine
Audio	AC97 Codec	AC97 Codec	AC97 Codec	AC97 Codec
Ethernet	Dual Realtek RTL8111B	VIA VT6103 100Base-Tx Fast Ethernet controller	Dual Realtek RTL8139C or optional Intel® 82559/82559ER 100Base-Tx Fast Ethernet controllers	Dual Realtek RTL8101L 100Base-Tx Fast Ethernet controllers
System Indicators	Power	Power	Power	Power
HDD	1 x 2.5" HDD	1 x 2.5" HDD	1 x 2.5" HDD	1 x 2.5" HDD
Serial Port	1 x RS-232, 1 x RS232/422/485 (Setting by BIOS)	2 x RS-232	1 x RS-232, 1 x RS-232/422/485	1 x RS-232, 1 x RS-232/422/485
Ethernet Port	2 x RJ-45	1 x RJ-45	2 x RJ-45	2 x RJ-45
VGA/LCD Port	1 x DB-15	1 x DB-15	1 x DB-15	1 x DB-15
Audio Port	Mic in, Line in, Line out	Mic in, Line in, Line out	Mic in, Line in, Line out	Mic in, Line in, Line out
USB Port	2 x USB 2.0	4 x USB 2.0	2 x USB 1.1	2 x USB 1.1
SATA Port	1 x SATA	n/a	n/a	n/a
Parallel Port	n/a	1 x DB-25	1 x DB-25	1 x DB-25
Mouse & KB	1 x PS/2 mini DIN	1 x PS/2 mini DIN	1 x PS/2 mini DIN	1 x PS/2 mini DIN
Power Input	100 ~ 240 Vdc / 50 ~ 60 Hz	100 ~ 250 Vdc / 47 ~ 63 Hz	100 ~ 250 Vdc / 47 ~ 63 Hz	100 ~ 250 Vdc / 47 ~ 63 Hz
Power Output	+5 Vdc / 8 A (40W)	5 Vdc / 5 A, 12 Vdc / 2 A (49W)	5 Vdc / 8 A (40W)	5 Vdc / 8 A (40W)

Diagram



Environment & Mechanical

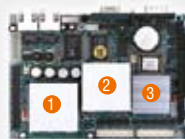
- **Operating Temperature** 0~40°C (32~104°F)
- **Storage Temperature** -20 ~ +75°C (-4~167°F)
- **Relative Humidity** 5 to 90% @ 40°C (104°F), relative humidity, non-condensing
- **Dimension (W x D x H)** 8.7" x 2.6" x 5.8" (220 mm x 65 mm x 147 mm)
- **Weight** 3.74 lbs (1.7 Kgs)
- **Mounting** Desktop

Ordering Information

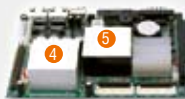
- **EES-3711**
VIA Eden V4 1 GHz Micro PC with Heatsink, VGA, Audio, 2 LAN, CF, 1 SATA, 2 COM & 2 USB 2.0
- **EES-3611**
VIA Eden ESP10K 1 GHz Micro PC with Heatsink, VGA, LCD, Audio, LAN, CF, 2 SATA, 2 COM & 4 USB 2.0
- **EES-3610B**
VIA Eden ESP6000 667 MHz Micro PC with Heatsink, VGA, LCD, Audio, Dual LAN, CF, 2 COM & 2 USB 1.1 (Blue Cover)
- **EES-3610B-E10**
Same as EES-3610B, but with Onboard VIA Eden ESP10K 1 GHz
- **EES-3512**
AMD Geode GX466 333 MHz Micro PC with Heatsink, VGA, Audio, Dual LAN, CF, 2 COM & 2 USB 1.1 (Silver Cover)

Special Thermal Module for Fanless Application

Avalve provides a smart thermal module that satisfies all applications requiring crucial heat dissipation. Three primary aluminum heatsink blocks cover all core components including CPU, south bridge, north bridge and clock generator.



1. CPU heatsink
2. North bridge heatsink
3. South bridge heatsink



4. Primary aluminum block and gap filler for heat conduction
5. Optional 2nd North bridge aluminum block for demanding 3D application



6. Customized aluminum block based on customer's height requirement



7. A cooling radiator beneath the outer cover absorbs heat from the main chipsets
8. Aluminum alloy enclosures and air ventilators further guarantee optimal heat dissipation

01
RISC

02
ETX

03
EPIC

04
3.5"

05
5.25"

06
MB

07
PC/104

08
Barebones

09
Smart
Terminal

10
InnoFlex
PPC

11
ACC